

Asia Pacific Advanced Packaging Market By Type (Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2),5D/3D and others), By End User (Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others), By Country, Industry Analysis and Forecast, 2020 - 2026

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Abstracts

The Asia Pacific Advanced Packaging Market would witness market growth of 12.9% CAGR during the forecast period (2020-2026).

The demand for compact electronic devices has increased in almost every sector, be it communication equipment, automotive, industrial or healthcare equipment. This trend has prompted semiconductor IC manufacturers to increase R&D investment in order to reduce the size and improve the output of ICs. This led to the advent of MEMS and 3D IC chips. In addition, over the decades, ICs have often been denser due to the growing number of interconnects and transistors requiring better deposition and patterning. Keeping up with the increased level of integration, engineers and designers are constantly designing new techniques for managing more circuitry and transistors within the same chip at the same expense, which has led to the development of emerging packaging technologies such as 3D packaging. The miniaturization of electronic devices will therefore have a relatively high impact on semiconductor device manufacturers, as current processing, manufacturing, research and assembly as well as packaging facilities will have to be upgraded in order to develop automated production systems for MEMS, 3D ICs and FinFET. As a result, the increased demand for compact electronic devices will drive market growth.

The chip scale package is a type of built-in circuit package. In order to qualify as a chip size, the package must have an area greater than 1.2 times that of the die and must be a single die, direct surface mountable package. The die can be mounted on an

interposer where the pads or balls are formed like a flip chip ball array packing. The pads may be etched or printed directly on the silicon wafer, resulting in a package that is very close to the size of the silicone die. This package is called a wafer-level kit (WLP) or a wafer-level chip-scale package.

Based on Type, the market is segmented into Flip-Chip Ball Grid Array, Flip Chip CSP, Wafer Level CSP, 2.5D/3D and Others. Based on End User, the market is segmented into Consumer Electronics, Automotive, Industrial, Aerospace & Defense, Healthcare & Life Sciences and Others. Based on countries, the market is segmented into China, Japan, India, South Korea, Singapore, Malaysia, and Rest of Asia Pacific.

The market research report covers the analysis of key stake holders of the market. Key companies profiled in the report include Qualcomm, Inc., Intel Corporation, IBM Corporation, Texas Instruments, Inc., Analog Devices, Inc., Renesas Electronics Corporation, Samsung Electronics Co., Ltd. (Samsung Group), Amkor Technology, Inc., Brewer Science, Inc., and MICROCHIP Technology, Inc.

Scope of the Study

Market Segmentation:

By Type

Flip-Chip Ball Grid Array

Flip Chip CSP

Wafer Level CSP

2.5D/3D

Others

By End User

Consumer Electronics

Automotive

Industrial

Aerospace & Defense

Healthcare & Life Sciences

Others

By Country

China

Japan

India

South Korea

Singapore

Malaysia

Rest of Asia Pacific

Companies Profiled

Qualcomm, Inc.

Intel Corporation

IBM Corporation

Texas Instruments, Inc.

Analog Devices, Inc.

Renesas Electronics Corporation

Samsung Electronics Co., Ltd. (Samsung Group)

Amkor Technology, Inc.

Brewer Science, Inc.

Microchip Technology, Inc.

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